Attorney Docket No. 042390.P5120D

In the Specification

Please change the title to:

METHOD OF ASSEMBLING A MULTI-CHIP DEVICE

A marked-up copy of the title is shown in Appendix A at the end of this response.

In the claims:

Please amend the claims as shown. A marked-up version of the amended claims is in Appendix A at the end of this document. A clean version of all pending claims after the amendment is shown below:

CLEAN VERSION OF CLAIMS AFTER AMENDMENT

19. (Amended nine times) A method of assembling a multi-chip device comprising:

populating a second surface of an interposer having a first surface and the second surface with a plurality of conductive pads;

coupling solder balls to selected ones of the plurality of conductive pads;

not coupling the solder balls to non-selected ones of the plurality of conductive pads, said non-selection being based on intended non-use of the non-selected ones;

coupling a plurality of cache memory devices and at least one passive device to the first surface to form a multi-chip subassembly, wherein the at least one passive device is selected from a group consisting of resistors,

2